100V N-Channel DTMOS

FEATURES

- Trench Power DTMOS Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Ontimized for Fast-switching Applications

Optimized for Fast-switching Applications		G G
APPLICATIONS	TO-251 S	so
 Synchronous Rectification in DC/DC and AC/DC Converters 	G	
 Isolated DC/DC Converters in Telecom and Industrial 		

Device Marking and Package Information			
Device	Package	Marking	
TSU10N10AT	TO-251	10N10AT	



Absolute Maximum Ratings $T_C = 25^{\circ}C$, unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage (V _{GS} = 0V)	V _{DSS}	100	٧
Continuous Drain Current	I _D	36	Α
Pulsed Drain Current (note1)	I _{DM}	144	Α
Gate-Source Voltage	V _{GSS}	±20	>
Single Pulse Avalanche Energy (note2)	E _{AS}	10	mJ
Avalanche Current (note1)	I _{As}	14	Α
Power Dissipation (T _C = 25°C)	P_{D}	56.5	W
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~+175	°C

Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R _{thJC}	2.1	00044
Thermal Resistance, Junction-to-Ambient	R _{thJA}	50	°C/W



Specifications $T_J = 25^{\circ}C$, unless otherwise noted						
Parameter Symbol Test Conditions	Symbol	Test Conditions	Value			Unit
		Min.	Тур.	Max.		
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	100			V
Zero Gate Voltage Drain Current	1	$V_{DS} = 95V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μΑ
Zero Gate Voltage Drain Guirent	I _{DSS}	$V_{DS} = 95V, V_{GS} = 0V, T_{J} = 150^{\circ}C$			100	
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 20V$			±100	nA
Gate-Source Threshold Voltage	$V_{\rm GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.1		2.5	V
Drain Course On Registeres (Note2)	D	$V_{GS} = 10V, I_D = 20A$		19	23	mΩ
Drain-Source On-Resistance (Note3)	R _{DS(on)}	$V_{GS} = 4.5V, I_{D} = 16A$		23	33	
Forward Transconductance (Note3)	g _{fs}	$V_{DS} = 5V, I_{D} = 20A$		40		S
Dynamic						
Input Capacitance	C _{iss}	V 0V		1134		
Output Capacitance	C _{oss}	$V_{GS} = 0V,$ $V_{DS} = 50V,$		92		pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		10.3		
T	Q _g (10V)			21		nC
Total Gate Charge	Q _g (4.5V)	$V_{DD} = 50V, I_{D} = 20A,$ $V_{GS} = 10V$		11		
Gate-Source Charge	Q_gs			3.1		
Gate-Drain Charge	Q_{gd}			5.1		
Turn-on Delay Time	t _{d(on)}			7		
Turn-on Rise Time	t _r	$V_{DD} = 50V, I_{D} = 20A,$		3		
Turn-off Delay Time	t _{d(off)}	$R_G = 3\Omega$		20		ns
Turn-off Fall Time	t _f			3		
Drain-Source Body Diode Characteri	stics		•	•		
Continuous Body Diode Current	Is				37	
Pulsed Diode Forward Current	I _{SM}	$T_{\rm C} = 25^{\rm o}{\rm C}$			148	А
Body Diode Voltage	V_{SD}	$T_J = 25^{\circ}C$, $I_{SD} = 1A$, $V_{GS} = 0V$		0.72	1	V
Reverse Recovery Time	t _{rr}	I _F = 20A,		25		ns
Reverse Recovery Charge	Q _{rr}	$di_{F}/dt = 500A/\mu s$		120		nC

Notes

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2. I_{AS} = 14A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 1%



Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted

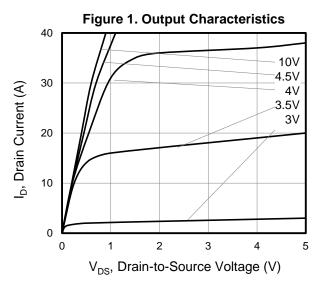


Figure 3. On-Resistance vs. Drain Current

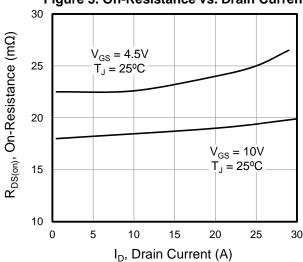


Figure 5. Gate Charge

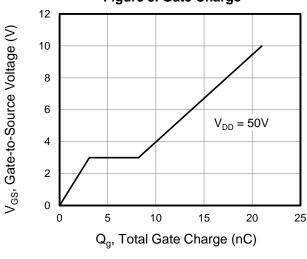


Figure 2. Transfer Characteristics

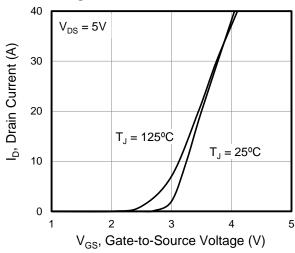


Figure 4. Capacitance

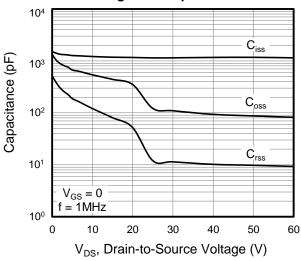
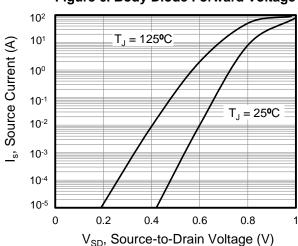


Figure 6. Body Diode Forward Voltage





Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Figure 7. On-Resistance vs. **Junction Temperature** 2.2 2 R_{DS(on)}, (Normalized) 1.8 $V_{GS} = 10V$ $I_D = 20A$ 1.6 1.4 $V_{GS} = 4.5V$ $I_{D} = 16A$ 1.2 1 0.8 50 75 100 125 0 25 150 175 T_J, Junction Temperature (°C)

Figure 8. Threshold Voltage vs. **Junction Temperature** 1.2 1.1 V_{GS(th)}, (Variance) $I_{D} = 250 \mu A$ 1 0.9 8.0 0.7 0.6 0 50 -100 -50 100 150 200 T_J, Junction Temperature (°C)

Figure 9. Transient Thermal Impedance

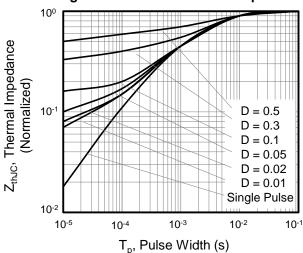




Figure A: Gate Charge Test Circuit and Waveform

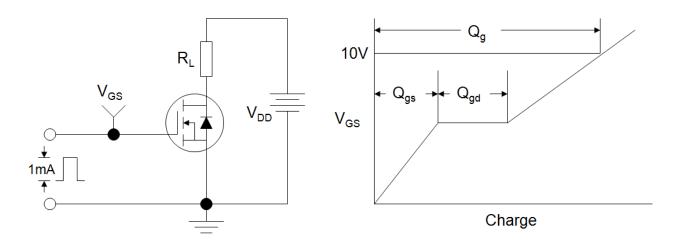


Figure B: Resistive Switching Test Circuit and Waveform

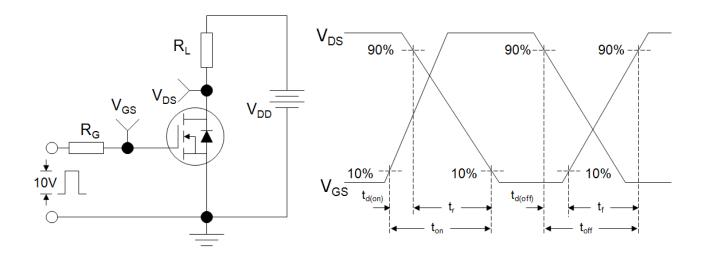
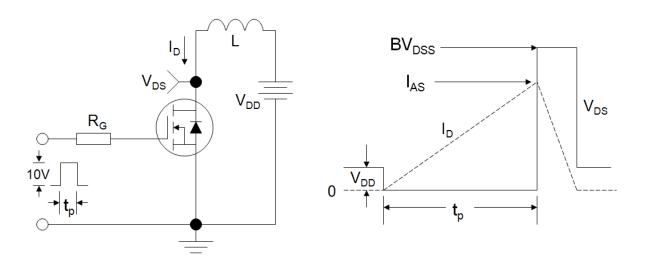
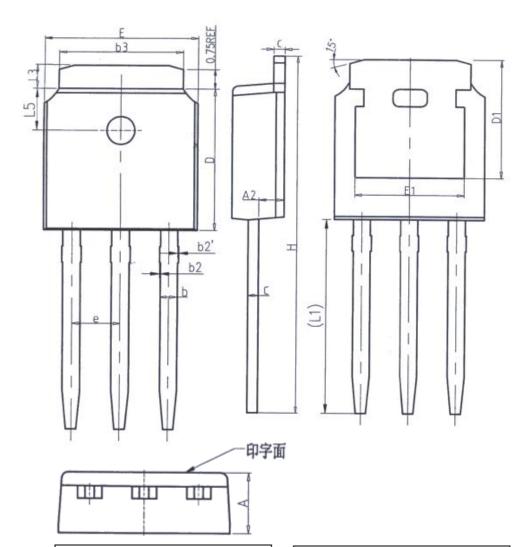


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





TO-251



Unit: mm			
Symbol	Min.	Max.	
Α	2. 20	2. 40	
A2	0. 97	1. 17	
b	0. 68	0. 90	
b2	0.00	0.10	
b2′	0.00	0.10	
b3	5. 20	5. 50	
С	0. 43	0. 63	
D	5. 98	6. 22	

Unit: mm			
Symbol	Min.	Max.	
D1	5. 30REF		
E	6. 40	6. 80	
E1	4. 63	-	
е	2. 286BSC		
Н	16. 22	16. 82	
L1	9. 15	9. 65	
L3	0.88	1. 28	
L5	1. 65	1. 95	



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